

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	$V_{RM}$	100	V
Peak Repetitive Reverse Voltage	$V_{RRM}$		
Working Peak Reverse Voltage	$V_{RWM}$	75	V
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(\text{RMS})}$	53	V
Forward Continuous Current (Note 4)	$I_{FM}$	500	mA
Average Rectified Output Current (Note 4)	$I_O$	250	mA
Non-Repetitive Peak Forward Surge Current @ $t = 1.0\mu\text{s}$	$I_{FSM}$	4.0	A
Non-Repetitive Peak Forward Surge Current @ $t = 1.0\text{s}$		1.0	

**Thermal Characteristics**

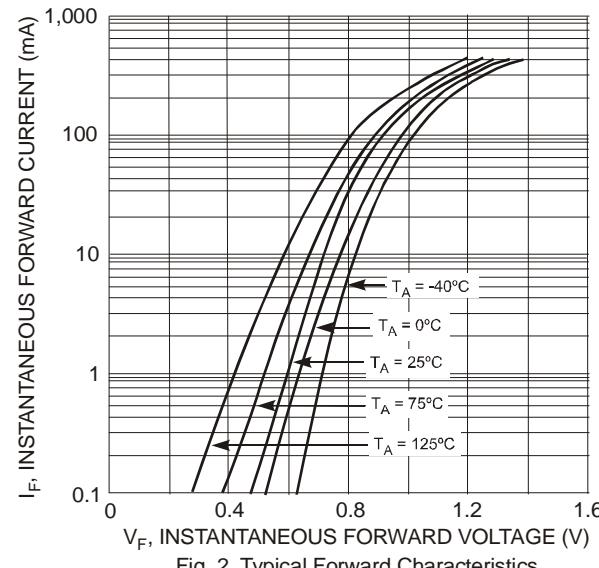
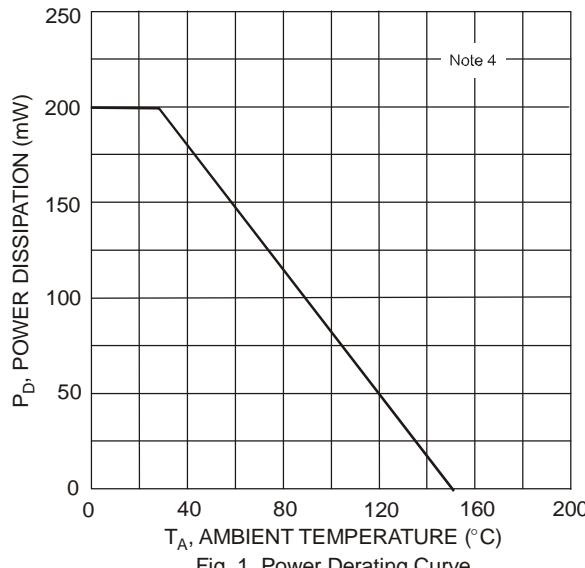
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	$P_D$	200	mW
Thermal Resistance Junction to Ambient Air (Note 4)	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	°C

**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	75	—	V	$I_R = 10\mu\text{A}$
Forward Voltage	$V_F$	0.62 — — —	0.72 0.855 1.0 1.25	V	$I_F = 5.0\text{mA}$ $I_F = 10\text{mA}$ $I_F = 100\text{mA}$ $I_F = 150\text{mA}$
Reverse Current (Note 5)	$I_R$	—	1.0 50 30 25	$\mu\text{A}$ $\mu\text{A}$ $\mu\text{A}$ nA	$V_R = 75\text{V}$ $V_R = 75\text{V}, T_J = 150^\circ\text{C}$ $V_R = 25\text{V}, T_J = 150^\circ\text{C}$ $V_R = 20\text{V}$
Total Capacitance	$C_T$	—	2.0	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{rr}$	—	4.0	ns	$I_F = I_R = 10\text{mA}$ , $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

Notes:

- 4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.
- 5. Short duration pulse test used to minimize self-heating effect.



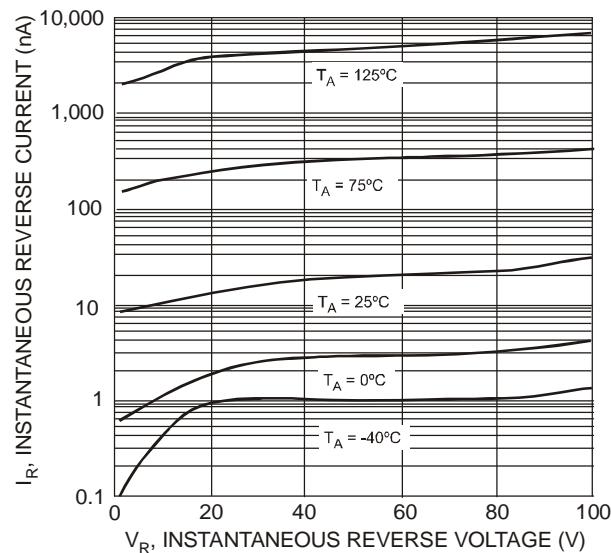


Fig. 3 Typical Reverse Characteristics

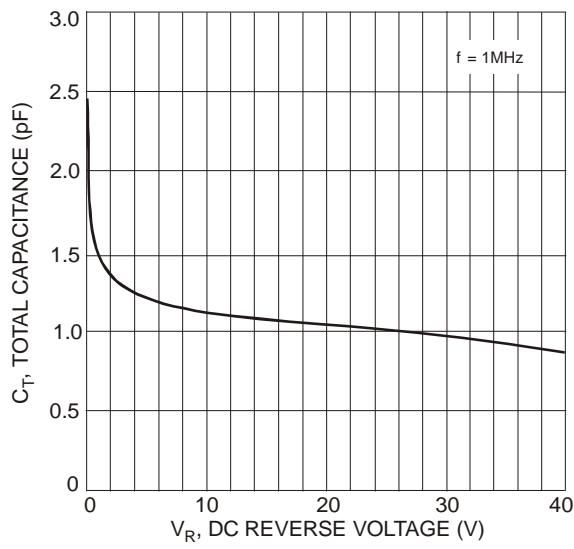
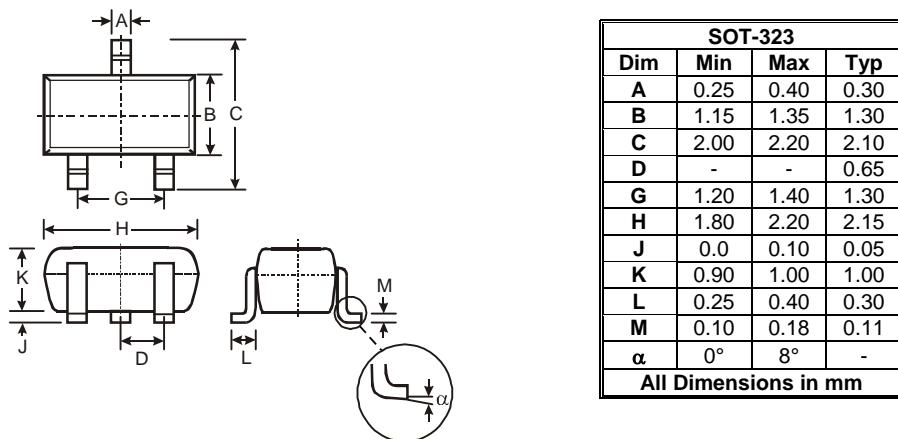
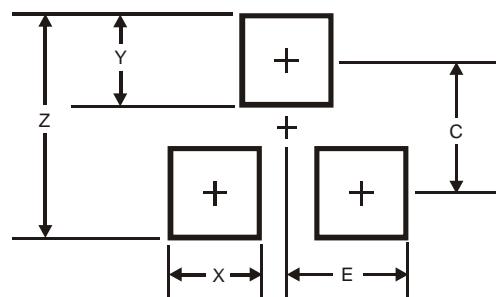


Fig. 4 Total Capacitance vs. Reverse Voltage

## Package Outline Dimensions



## Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.8
X	0.7
Y	0.9
C	1.9
E	1.0

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